



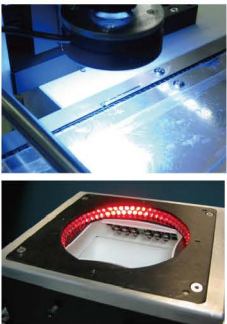
ANS-Series

Optical Inspection Check System

www.dediprogram.com

AOI-632/ANS-640-B/ANS-640C-B (2D)/ANS-680 (3D)

Inspect the tiny details of the IC chips



DediProg provides different kinds of automatic optical inspection systems. Integrate one of these systems with DediProg's automated programming system, it will be easy to examine the IC conditions while programming, either from the top or from the bottom, 2D or 3D.

Functions

Leadscan- skew, total length, pin pitch, or bent pins.

Mark Inspection- error, wrong direction, large scratches, or no labels.

Package Inspection- package size, big chipping, chip crack (0.03mm), scratch, dirt, fall off, broken, or blurred.

Ball Inspection- dirt between, void, pin count, circuit track, ball missing, ball size roundness, defect, bend, different height, area, pitch, offsets, diameter, or circumference of the ball.

3D Inspection

- 3D high-definition, multi-camera, triangulation technology
- Multi-spectral LED strobe lighting
- Simultaneous multi-part & ROI Capability increases throughput
- Leaded, BGA & QFN package & supported (5S QFN option available)
- No hardware change-over required between package types
- Able to check Lead floated

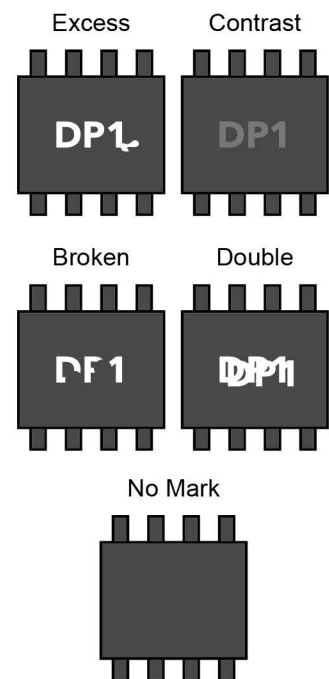
Advantages of 2D Inspection:

1. Mature technology
2. Cost-effective
3. High speed
4. Less susceptible to shadowing issues
5. Flexible inspection capabilities

Advantages of 3D Systems:

1. True co-planarity inspection capability
2. Reduced false call rate

Orientation & Marking



DediProg Technology Co., Ltd.

Taiwan Headquarter
 T/ 886-2-2790-7932
 E/ sales@dediprogram.com

China
 T/ 86-21-5160-0157
 E/ sales@dediprogram.com.cn

Korea
 T/ 031-275-3838
 E/ korea@dediprogram.com

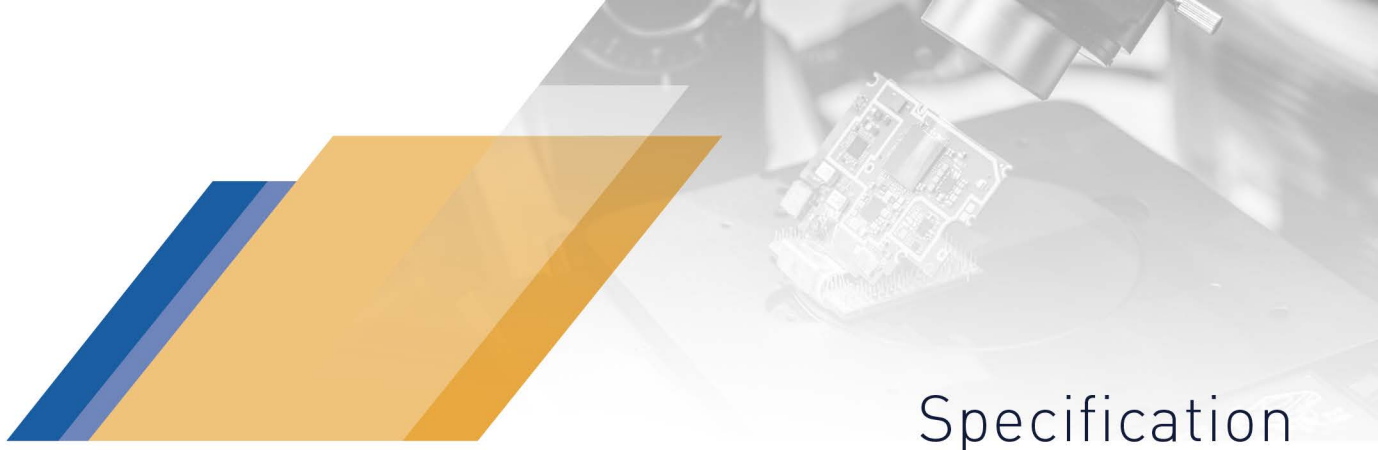
Malaysia
 T/ 607-288-1998
 E/ sales@dediprogram.com

U.S.
 T/ 1-909-274-8860
 E/ america@dediprogram.com

Europe
 E/ europe@dediprogram.com

Japan
 E/ japan@dediprogram.com





Specification

Model	A0I-632	ANS-640-B	ANS-640C-B	ANS-680
View (mm)	32x24	28x22	6x6	50x50
Light Control	✗	✗	✗	✓
Image Capturing	Top	Bottom	Bottom	Bottom
Leads can	✗	✓	✗	✓
Mark Inspection	✓	✗	✗	✗
Package Inspection	✗	✓	✓ (IC body cracked/defective)	✓
Ball Inspection	✗	✓	✓	✓
Supported Packages	All (Except for the CSP that has glossy surface)	BGA, CSP, QFN, SOP, QFP	BGA (smaller than 5x5mm) CSP	QFN, SOP, QFP, BGA, CSP
Installation	on DP600 Reel out position or AutoTray-350 tray out position	on handler	on handler	on handler

